

< High Resolution SMU >

Designed By: Yuheon Yi

Checked & Approved By: YK Seul & Donghyuk Yoo

Ver 1.1 : 2021.07.23

검색 TEXT:

회로도 설명

검색 TEXT : 회로도 수정포인트 (두꺼운 박스 -

이런버전 에서 수정된 부분)

판색 TEXT : PCB Si 키표시 [중 팔호

판색 TEXT :

회로블럭 이름

02. Revision History

03. Connector and Power

04. Buffer

05. FPGA #1

06. FPGA #2

07. FPGA #3

08. DAC

09. ADC and Measurement Circuit

10. ERROR AMP

11. POWER AMP

12. OUTPUT CONTROL

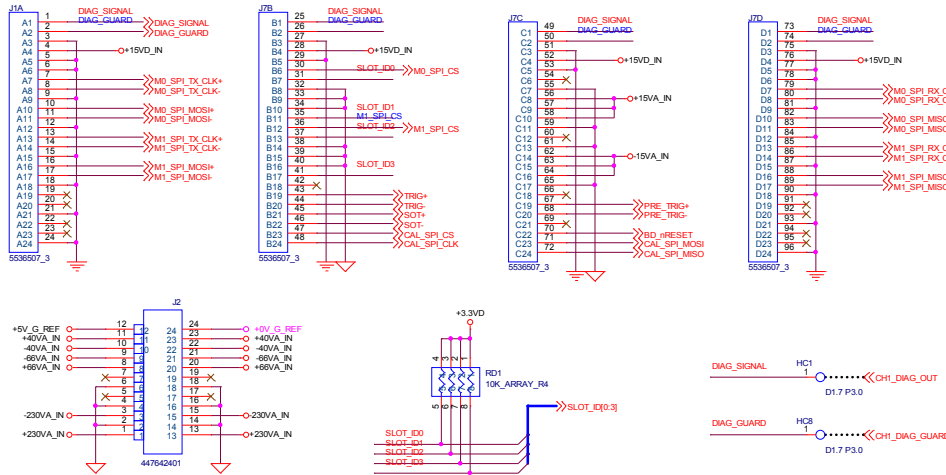
13. OUTPUT

14. JIG

<Revision History >

Date	Version	Editor	Revision
2019.09.16	1.0	Y00 DH	24bit Resoultion ADC & New Range (500mV, 10pA)
2021.07.20	1.1	YH YI	200V 10mA max range. S3100 interface. 20bit DAC

INPUT CONNECTOR



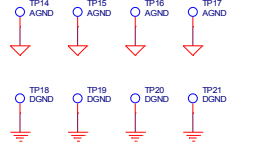
GND 연결



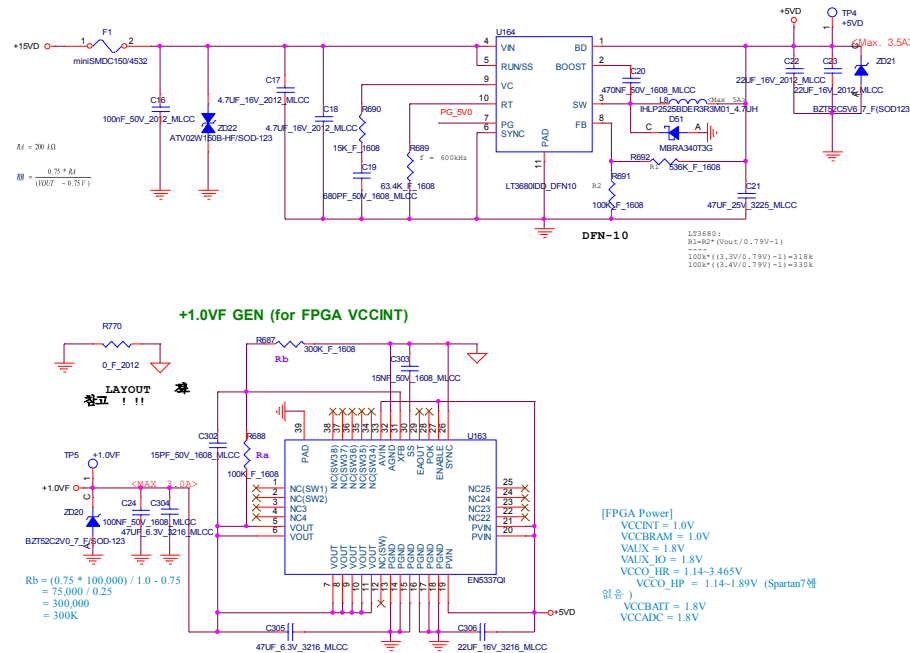
15V IN



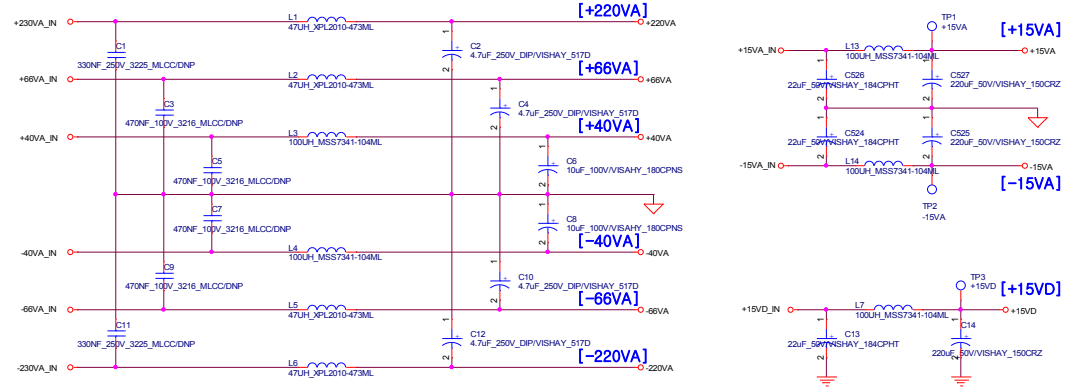
TP - GND



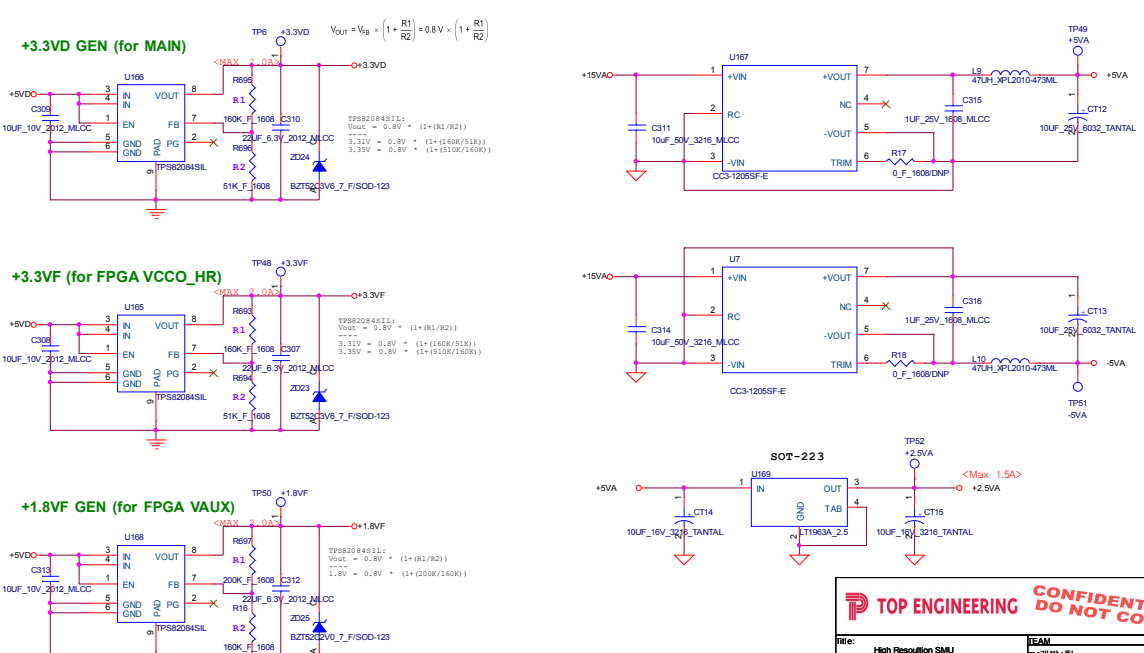
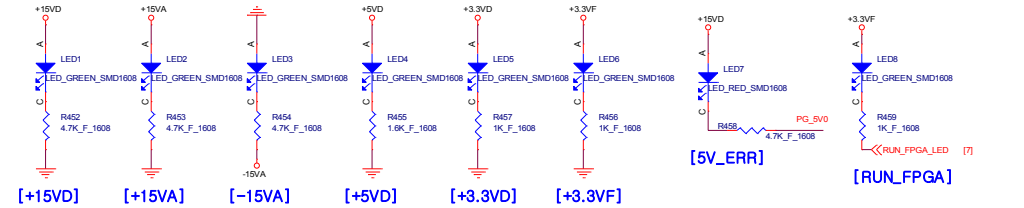
REGULATOR

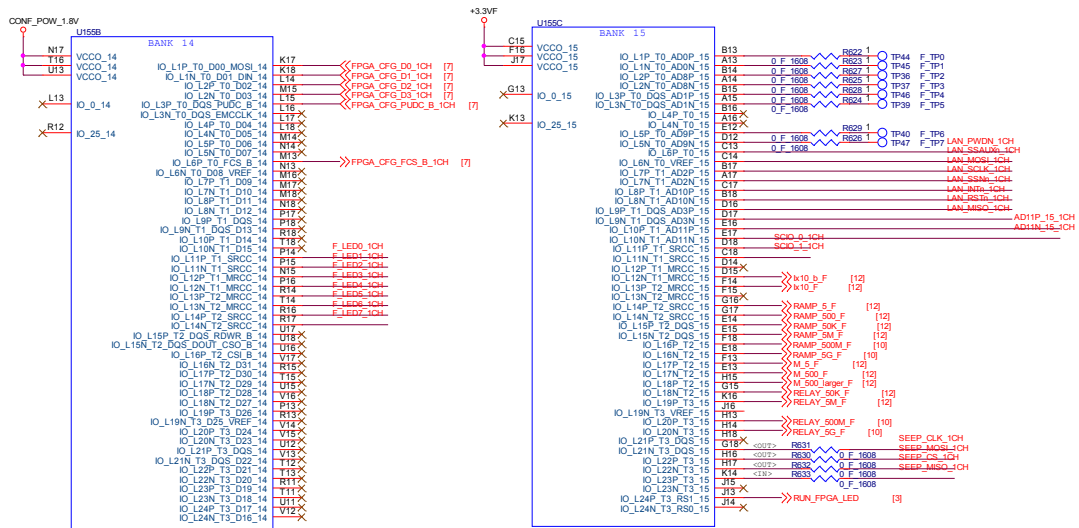


POWER FILTER



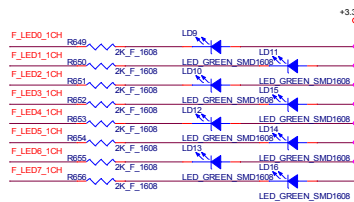
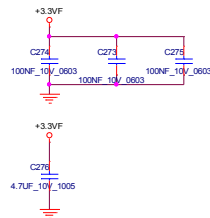
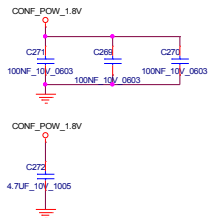
POWER LED & RUN LED





xc7s50-1csga324i

xc7s50-1csga324i

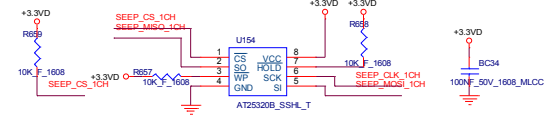


[F_LED0]

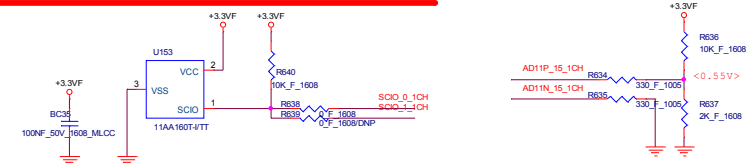
[F_LED7]

SPI EEPROM(1CH)

Calibration DATA 저장용 Serial EEPROM

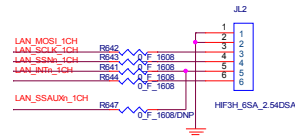


EEPROM 16K 2048X8 1.8V SERIAL EE IND(1CH)

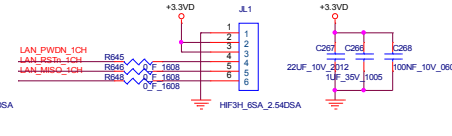


LAN 埠 Connector(1 CH)

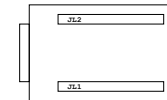
to. WIZ850 J1



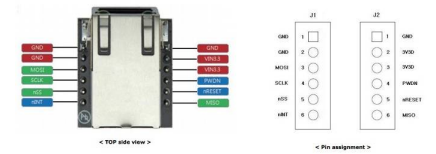
to. WIZ850 J2



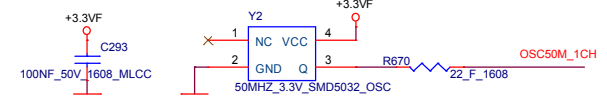
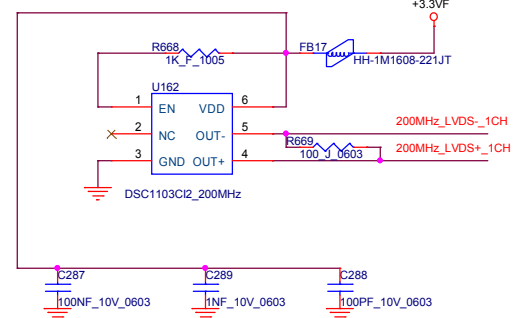
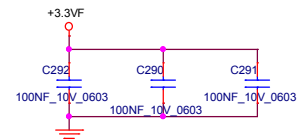
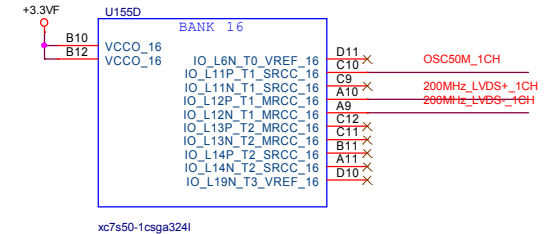
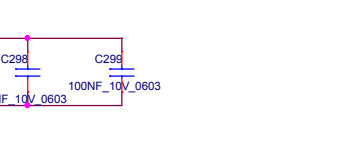
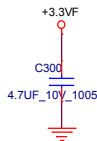
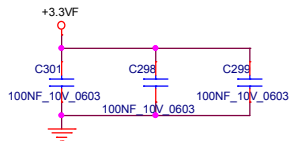
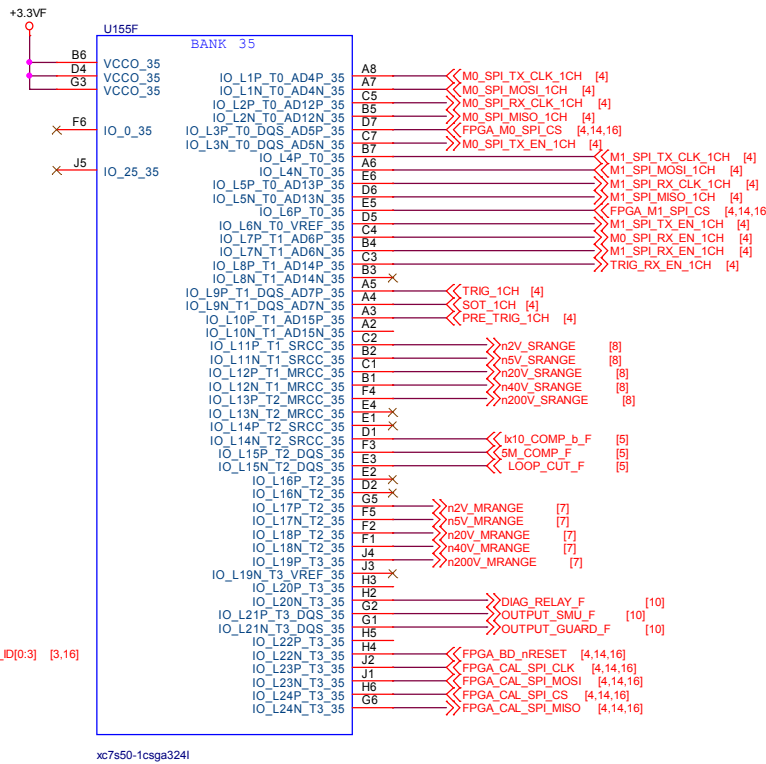
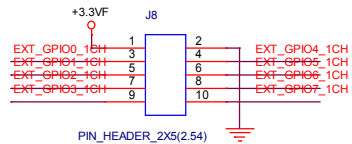
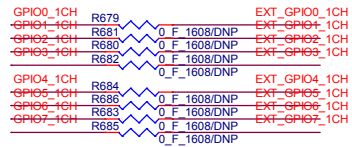
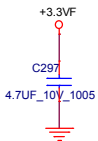
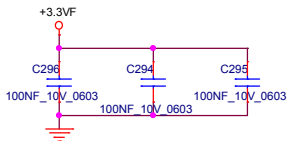
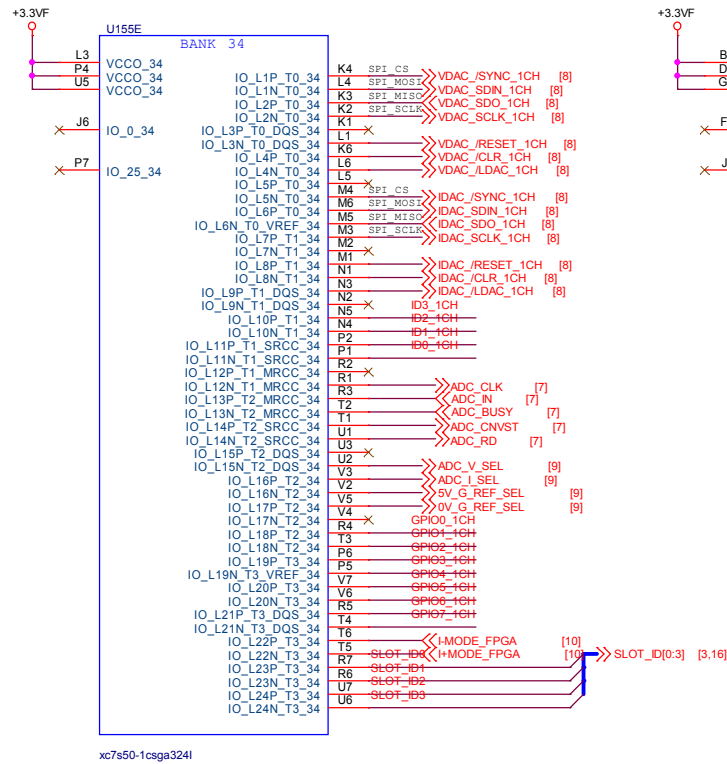
폴링방식 으로 구 동
RST클레이 initia lize or re-initia lize W
또는 IN클레이 하에 동 작 직 용



Pin Assignment

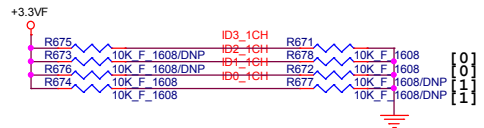


FPGA IO(1CH)



Artwork 작 업 시 한 곳 에 도주세요

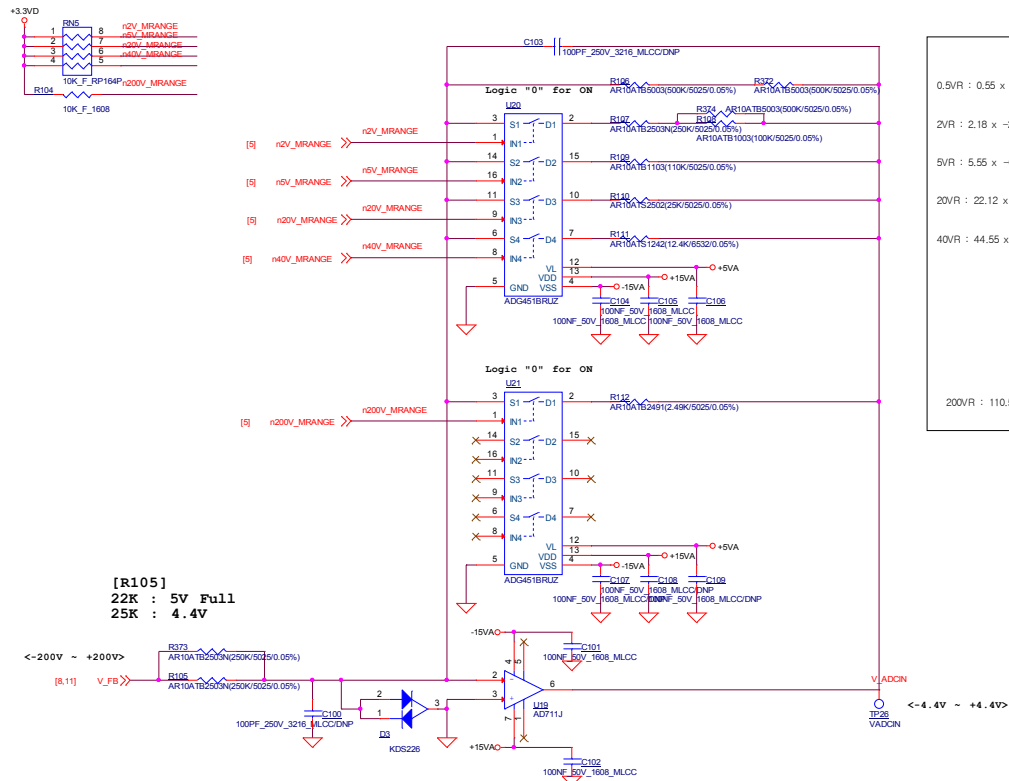
Siik : SMU BD ID : 0x0?
<LSB 4Bits>



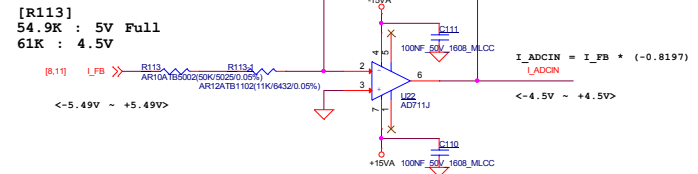
SMU BD ID 확 인 하 여 저 항 플 업 /다 음

TOP ENGINEERING					CONFIDENTIAL	
DO NOT COPY						
Title:	High Resolution SMU				TEAM	
Size	Document	Number	Designed		Checked	Approved
A3	06. FPGA#2 (XC6SL59)		DH YOO		Seol YK	DH YOO
Date:	Tuesday, July 27, 2021				Sheet	6 of 12

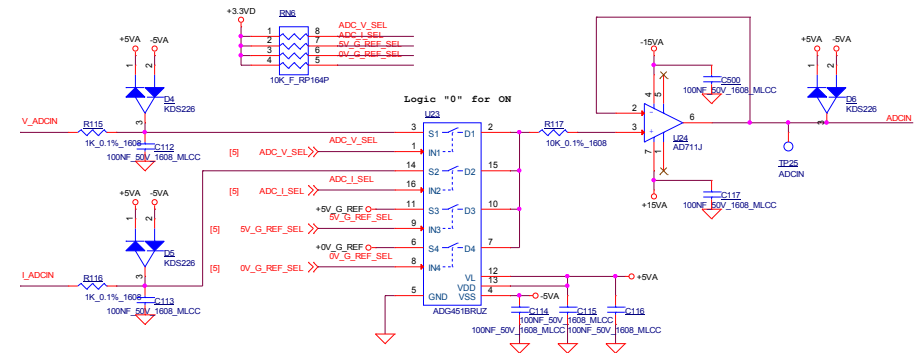
VM RANGE



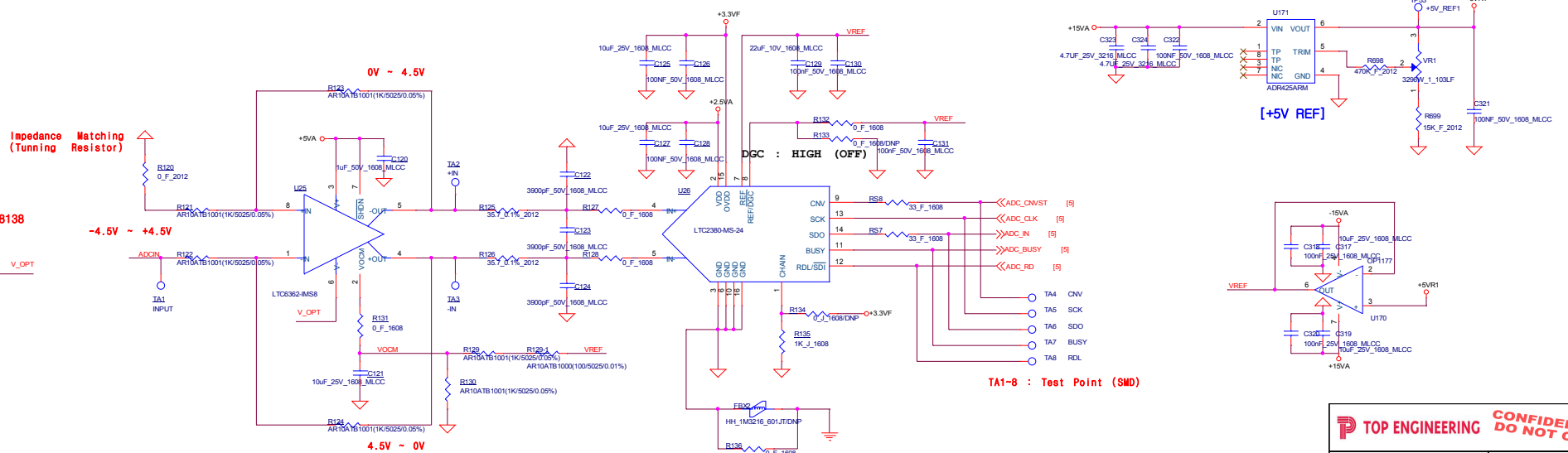
I_ADCIN



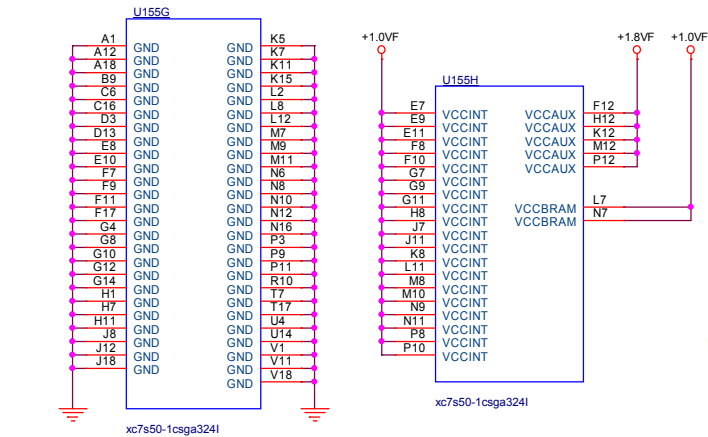
ADC SEL



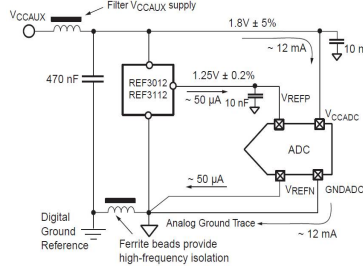
HR ADC



FPGA - POWER(1CH)



[FPGA Power]
VCCINT = -0.5~1.1 [1.0V]
VCCBRAM = -0.5~1.1 [1.0V]
VCCAUX = -0.5 ~ 2.0V [1.8V]
VCCAUX_IO = -0.5 ~ 2.0V [1.8V]
VCCO_HR = 1.14~3.465V
VCCO_HP = 1.14~1.89V (Spatan7
없음)
VCCBATT = -0.5 ~ 2.0V [1.8V]
VCCADC = -0.5 ~ 2.0V [1.8V]



VCCBATT is required only when using bitstream encryption.
If battery is not used, connect VCCBATT to either ground or VCCAUX.

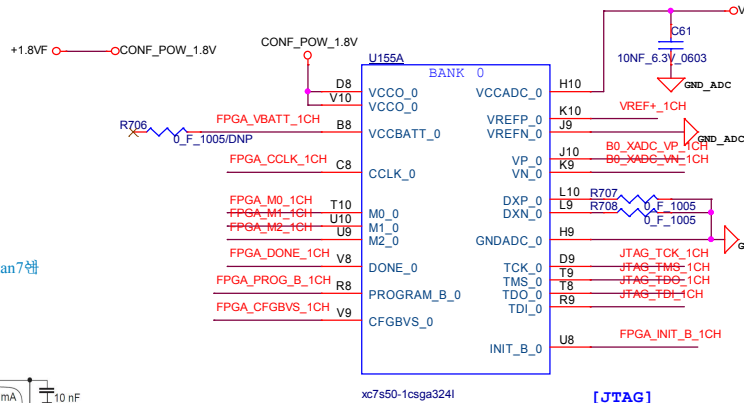
If the VCCO_0 supply for bank 0 is supplied with 2.5V or 3.3V, then the CFGBVS pin must be tied High (i.e. connected to VCCO_0). Tie CFGBVS to Low (i.e. connected to GND), only if the VCCO_0 for bank 0 is less than or equal to 1.8V. If used during configuration, banks 14 and 15 should match the VCCO level applied to bank 0

Program (bar)
Active-Low reset to configuration logic. When PROGRAM_B is pulsed Low, the FPGA configuration is cleared and a new configuration sequence is initiated. Configuration reset initiated upon falling edge, and configuration (i.e. programming) sequence begins upon the following rising edge.
Connect PROGRAM_B to an external ≤ 4.7 k Ω pull-up resistor to VCCO_0 to ensure a stable High input, and recommend push-button to GND to enable manual configuration reset.

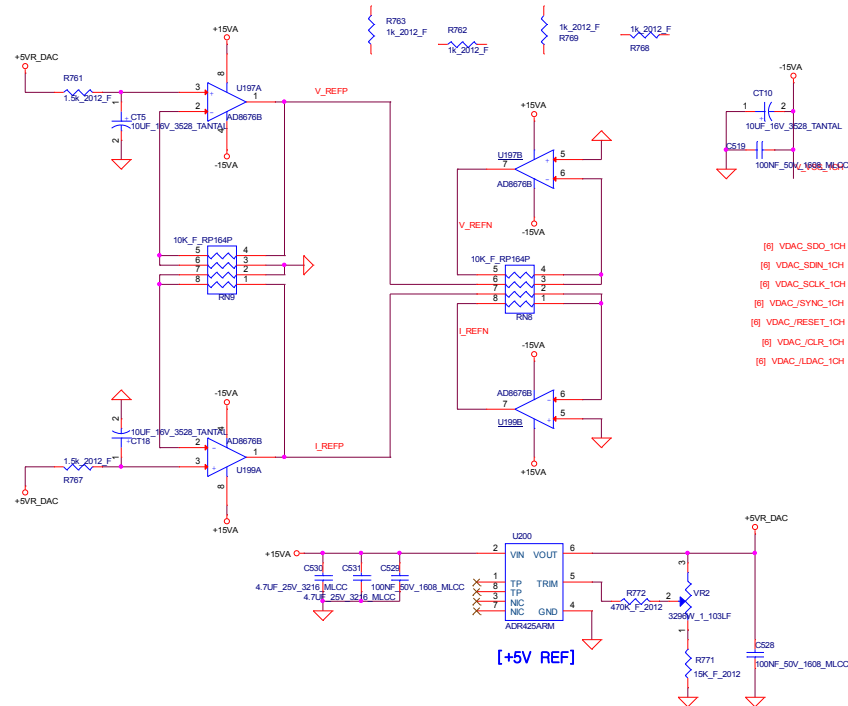
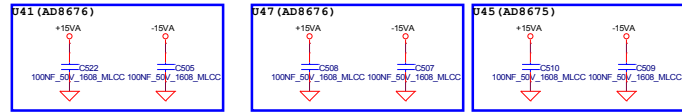
Initialization (bar)
Active-Low FPGA initialization pin or configuration error signal. The FPGA drives this pin Low when the FPGA is in a configuration reset state, when the FPGA is initializing (clearing) its configuration memory, or when the FPGA has detected a configuration error. Upon completing the FPGA initialization process, INIT_B is released to high-Z at which time an external resistor is expected to pull INIT_B High. INIT_B can externally be held Low during power-up to stall the power-on configuration sequence at the end of the initialization process. When a high is detected at the INIT_B input after the initialization process, the FPGA proceeds with the remainder of the configuration sequence dictated by the M[2:0] pin settings.
Connect INIT_B to a ≤ 4.7 k Ω pull-up resistor to VCCO_0 to ensure clean Low-to-High transitions.

Done
A High signal on the DONE pin indicates completion of the configuration sequence. The DONE output is an open-drain output by default.

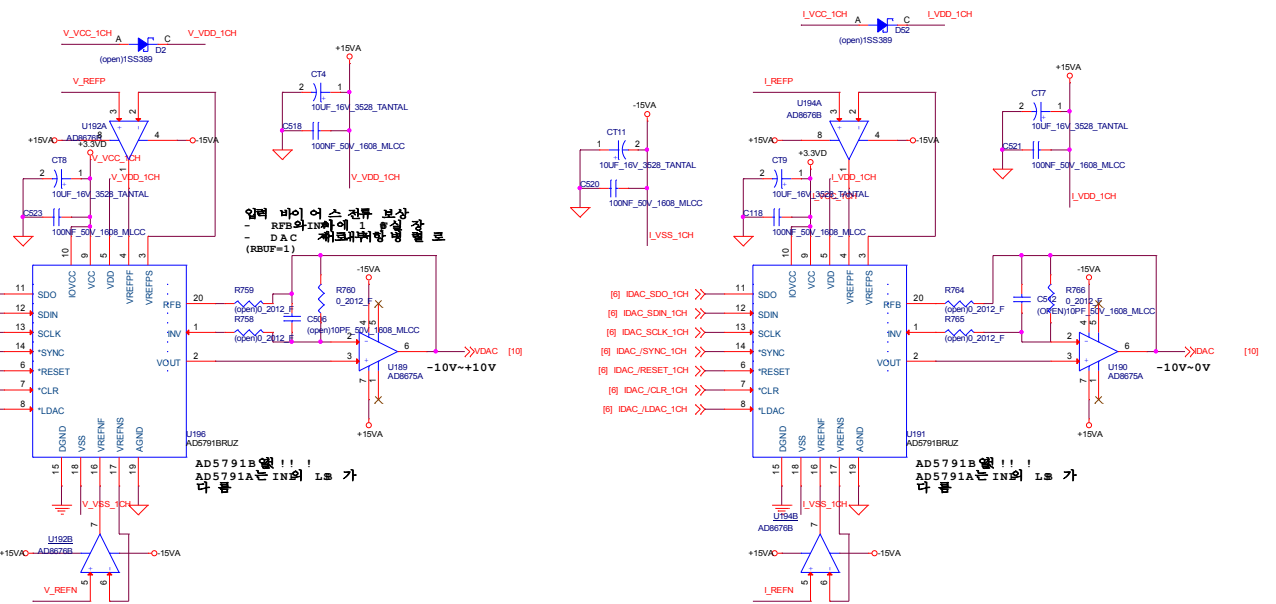
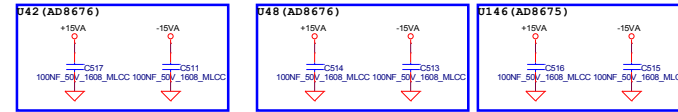
FPGA - Configuration Part(1CH)



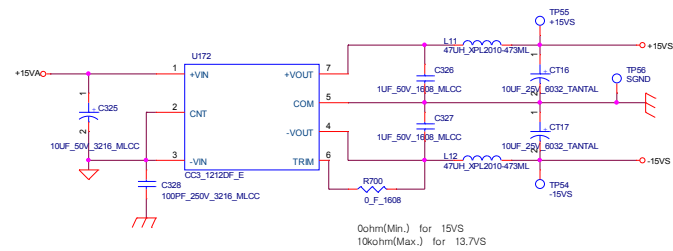
VDAC(1CH)



IDAC(1CH)



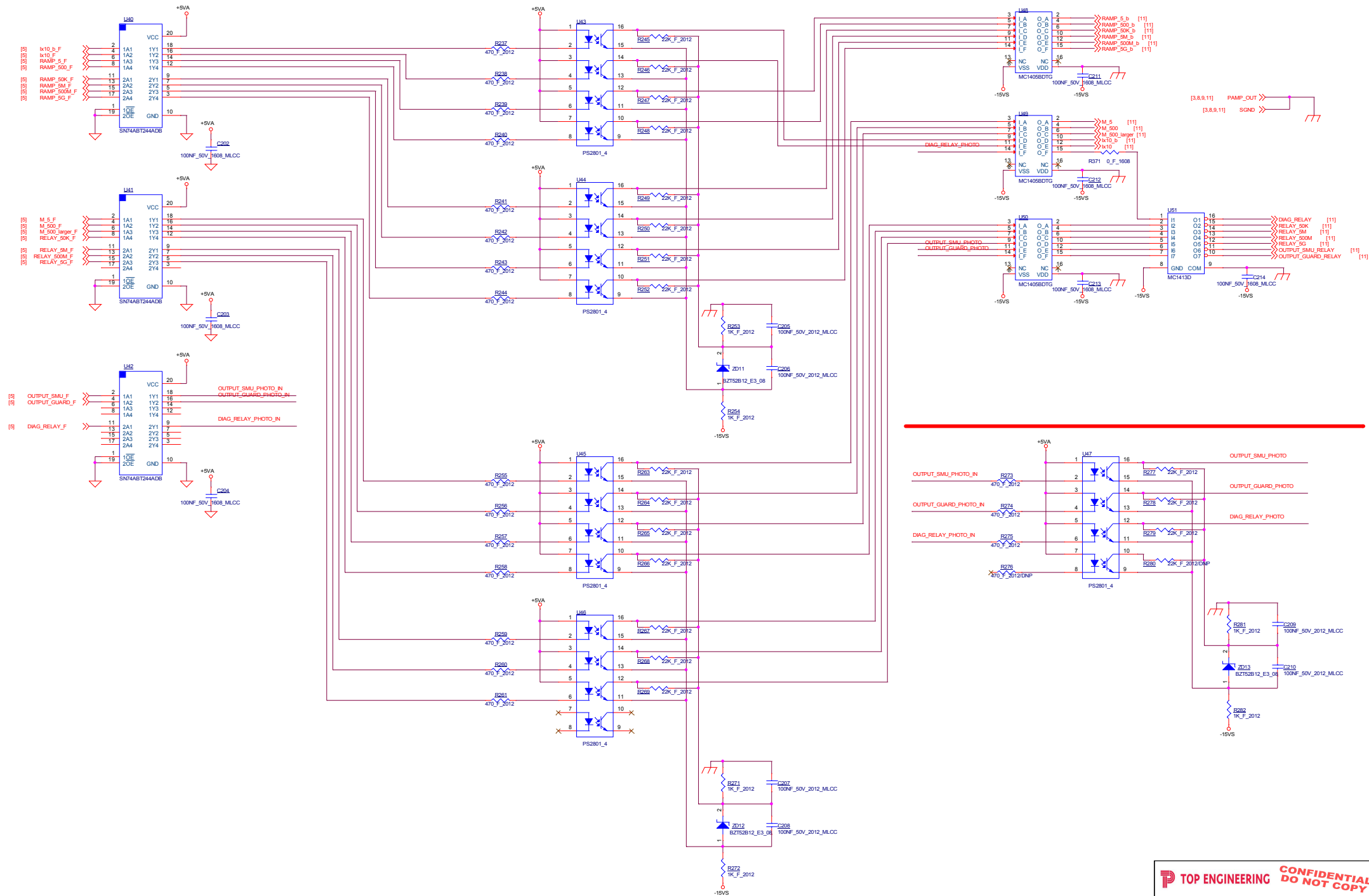
Isolated DC-DC Converter (Floating Power)



CONTROL SIGNAL BUFFER

SIGNAL ISOLATE

I RANGE CONTROL

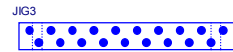




PERPIN_POGO_PIN_COVER



HRSMU_INPUT_SHIELD_COVER



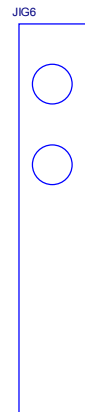
HRSMU_SHIELD_COVER



HRSMU_BOTTOM



HRSMU_AMP_COVER



HRSMU_FRONT_COVER

Tri Axial 측정 홀

CUT11



CUT_W4.0 H2.5

CUT12



CUT_W4.0 H2.5

CUT13



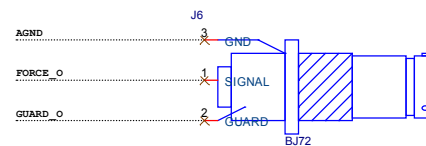
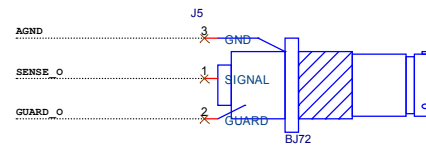
CUT_W4.0 H2.5

CUT14



CUT_W4.0 H2.5

전면 판
기척터



PST에 연결된 전면 판 Tri axial
캐릭터 (BJ72)에 연결

TOP ENGINEERING				CONFIDENTIAL DO NOT COPY			
Title:		High Resolution SMU			TEAM		
Size		Document Number			TM개발1팀		
A3		12. JIG			Designed	Checked	Approved
Date:		Monday, July 26, 2021			Seol YK	Seol YK	DH YOO
					Sheet	12	of 12
					Rev		
					1.0		